

# LEADFRAME-BASED NON-LEADED SEMICONDUCTOR PACKAGE AND METHOD OF FABRICATING THE SAME

## ABSTRACT OF THE DISCLOSURE

A leadframe-based non-leaded semiconductor package and method of fabricating the same is proposed, which is used for the fabrication of a non-leaded type of semiconductor package, such as QFN (Quad Flat No-lead) package. The proposed semiconductor packaging technology is characterized by the provision of a recessed portion in the paddle portion of the leadframe to help secure the encapsulation body more firmly in position without delamination, as well as help lower the position of the packaged chip to help prevent the bonding wires from being exposed to the outside of the encapsulation body. These features can help the finished package to be more reliable with increased good yield..

\* \* \* \* \*